

Name : .....

Roll No. : .....

Invigilator's Signature : .....

**CS/B.TECH(ME)/SEP.SUPPLE/SEM-7/ME-701/2012**

**2012**

**ADVANCED MANUFACTURING TECHNOLOGY**

Time Allotted : 3 Hours

Full Marks : 70

*The figures in the margin indicate full marks.*

*Candidates are required to give their answers in their own words  
as far as practicable.*

**GROUP – A**

**( Multiple Choice Type Questions )**

1. Choose the correct alternatives for the following :  $10 \times 1 = 10$ 
  - i) Mechanics of material removal in EDM is
    - a) melting and evaporation aided by cavitation
    - b) mechanical cutting action
    - c) melting
    - d) electrolysis.
  - ii) Which one of the following is a binary sensor ?
    - a) Accelerometer
    - b) DC Tachometer
    - c) Proximity switch
    - d) Thermistor.
  - iii) Diamond tools should be used for high speed machining of
    - a) cast iron jobs
    - b) mild steel jobs
    - c) aluminium jobs
    - d) carbide jobs.

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- iv) CAPP is fully integrated with
  - a) CAD and CAM
  - b) only CAD
  - c) only CAM
  - d) none of these.
- v) The hardest manufactured cutting tool material is
  - a) diamond
  - b) ceramic
  - c) carbon boron nitride
  - d) tungsten carbide.
- vi) The fundamental philosophy of Computer Integrated Manufacturing is
  - a) Sequential Engineering
  - b) Concurrent Engineering
  - c) Reserve Engineering
  - d) Value Engineering.
- vii) The mechanism of AGV is based on the principle of
  - a) acoustic emission
  - b) embedded wire guided method
  - c) interferometry
  - d) triangulation.
- viii) The dielectric fluid is used in
  - a) ECM
  - b) USM
  - c) AJM
  - d) EDM.
- ix) In EBM process, the maximum material removal rate is
  - a)  $20 \text{ mm}^3/\text{min}$
  - b)  $30 \text{ mm}^3/\text{min}$
  - c)  $10 \text{ mm}^3/\text{min}$
  - d)  $40 \text{ mm}^3/\text{min}$ .
- x) Lower machining accuracy is obtained in
  - a) PAM
  - b) LBM
  - c) EBM
  - d) EDM.

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**GROUP – B****( Short Answer Type Questions )**Answer any *three* of the following.  $3 \times 5 = 15$ 

2. With a simple diagram explain the working of Plasma Arc Machining.
3. a) What do you mean by flexible manufacturing system ?  
b) Define rapid prototyping.  $3 + 2$
4. Use successive approximation method to convert an input signal of 6.8 V from analog to digital signal for a 6-bit Register of an ADC with a full scale range of 10 V.
5. Write down the benefits of FMs.

**GROUP – C****( Long Answer Type Questions )**Answer any *three* of the following.  $3 \times 15 = 45$ 

6. a) Draw the resistance-capacitance relaxation circuit used in EDM. Show the variation of instantaneous voltage across the tool-workpiece gap along with the time. Prove that  $V = V_0 \left\{ 1 - e^{-\frac{t}{RC}} \right\}$ . Notations have their usual meanings.
- b) During an electric discharge drilling of a 10 mm square hole in a low carbon steel plate of 5 mm thickness, brass tool and kerosene are used. The resistance and the capacitance in the relaxation circuit are  $50 \Omega$  and  $10 \mu\text{F}$ , respectively. the supply voltage is 200 volts and the gap is maintained at such a value that the discharge (sparking) takes place at 150 volts. Estimate the time required to complete the drilling operation. Use the correlation  $Q = 27.7 W^{1.54}$ .  $(2 + 2 + 4) + 7$

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7. a) Describe the fundamental principles of metal removal in Electro-chemical Machining. Briefly explain the significance of Electrolyte used in ECM and also the importance of 'Tool-work gap'.
- b) Discuss the mechanism of material removal for Abrasive Jet Machining. How to select the best possible abrasive and nozzle material to be used in this process ?
- c) Write a note on the special features of the equipments used in Water Jet Machining. 4 + 2 + 4 + 2 + 3
8. a) Explain the main factors that affect the AJM removal rate.
- b) Explain LBM and show using a line sketch, the material removal mechanism of the process.
- c) State three commonly used graphics standards and mention their advantages with reference to specific application. 3 + 7 + 5
9. a) Explain the selective layer sintering process.
- b) Under what circumstances is Reverse Engineering recommended ?
- c) Explain with a neat sketch the geometry of a drilled hole using LBM. 5 + 5 + 5
10. a) Explain detail integration of CAD with CAM.
- b) Describe the basic principle of operation of AGV.
- c) List application of AGV in CIM. 6 + 5 + 4

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